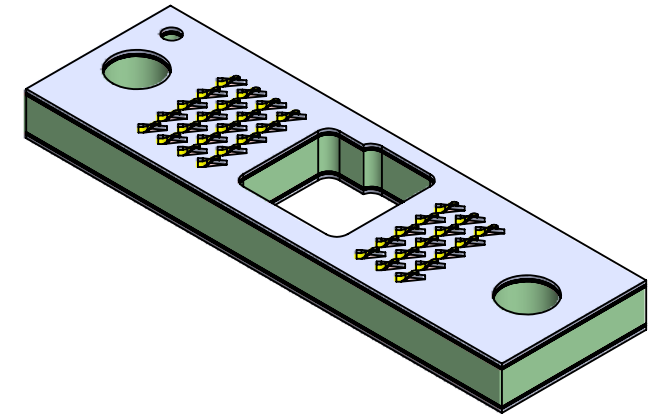
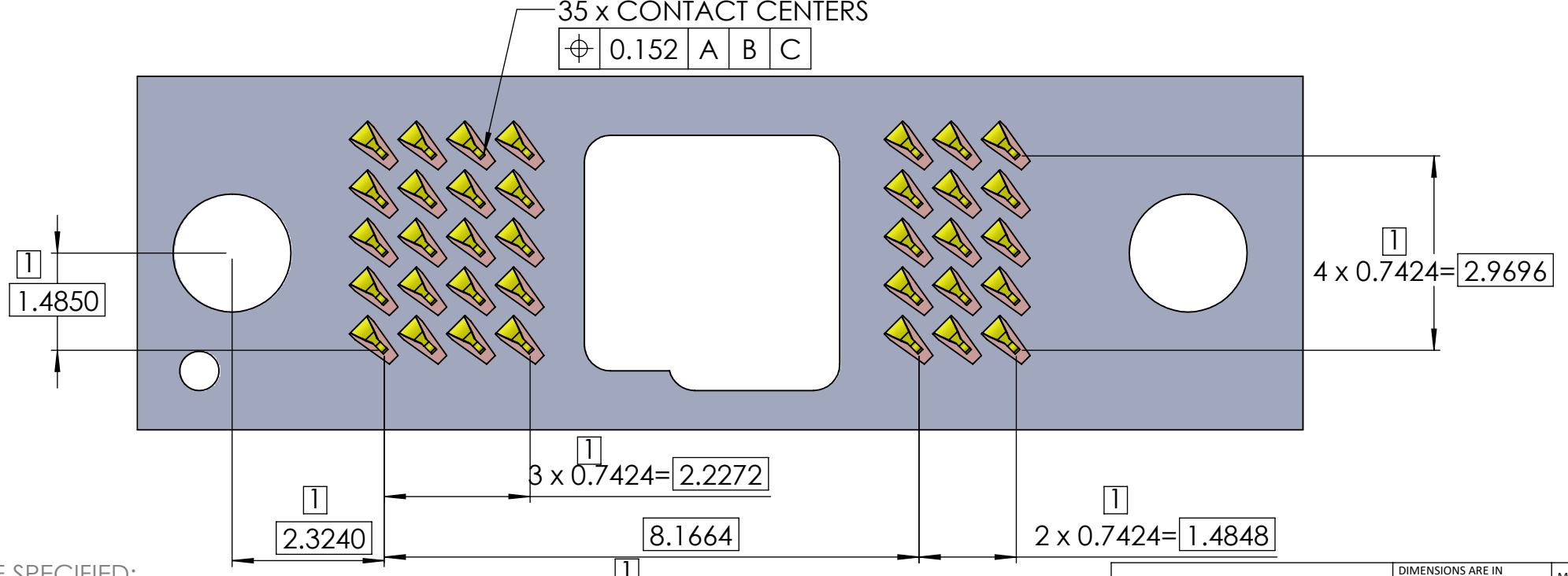
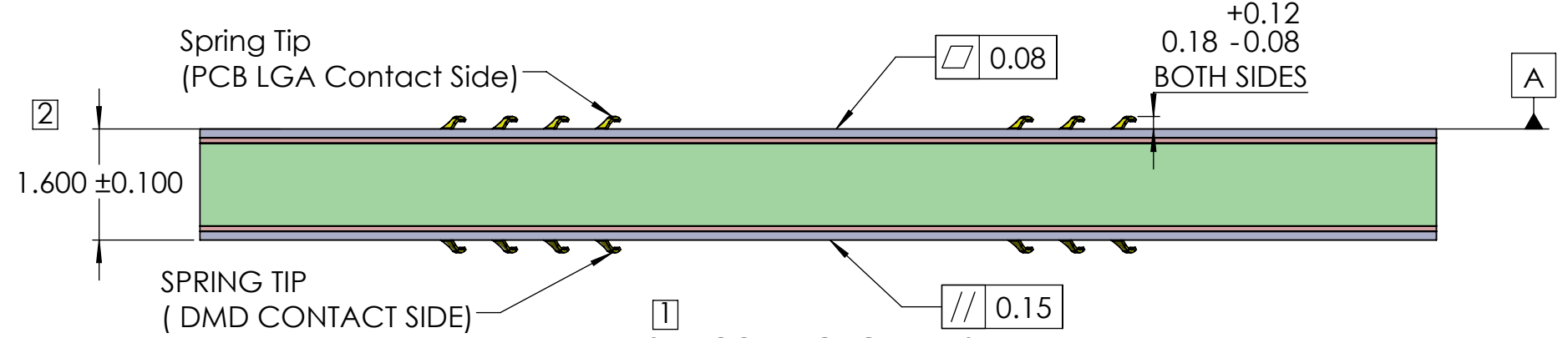
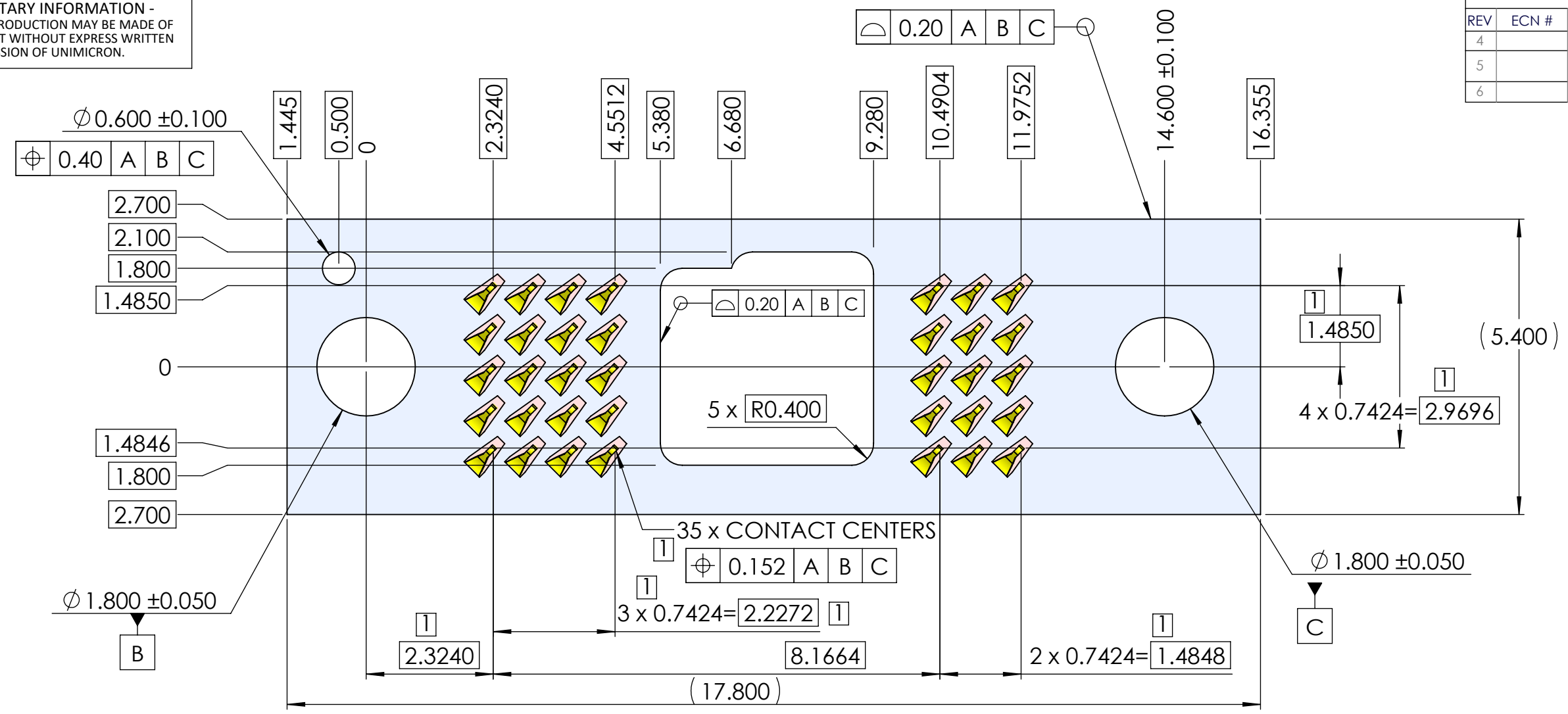


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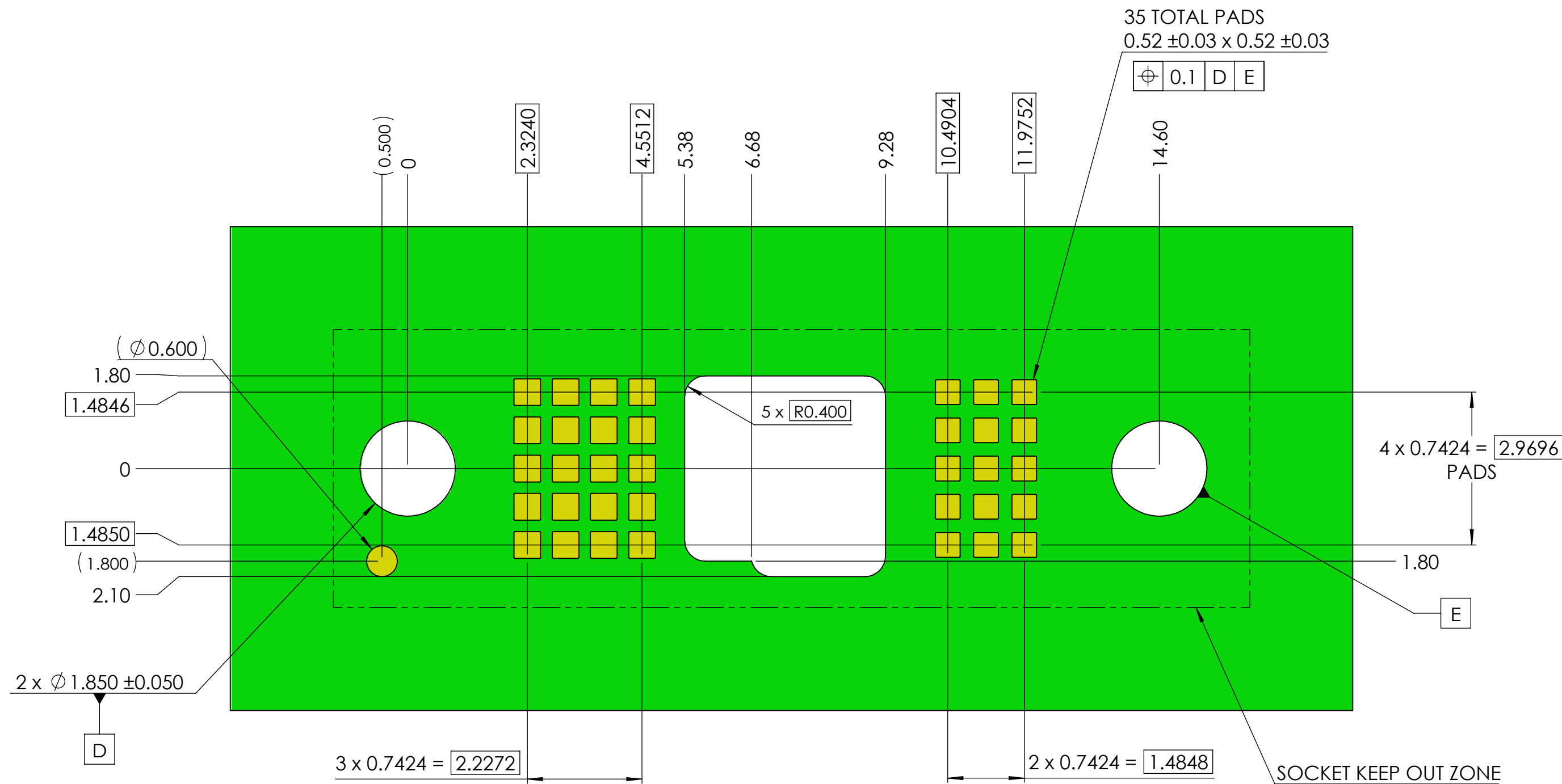
Revisions			
REV	ECN #	Description	Date
4		Update inside R from 0.3 to 0.4	2021/04/20
5		1. Add PCB footPrint 2. Add package information	2022/02/17
6		Add DMD footPrint	2022/02/18



- NOTES: UNLESS OTHERWISE SPECIFIED:
1. Interpret Drawing Per ASME Y14.5-94
 2. Compliant With RoHS Directive 2011/65/EU
 3. Center Position Of The Contact Area In The Compressed State
 4. Height When Contacts Are Fully Compressed Between DMD And PCB



DIMENSIONS ARE IN MM		MATERIAL:		TITLE:	
.X ± 0.15	✓	FINISH: --		35 positions LGA-LGA PCBeam interposer (0.7424 mm pitch)	
.XX ± 0.10		DRAWN BY: Winni Cheng 2022/02/18		SIZE	
.XXX ± 0.05		CHECKED BY: Jason Wu 2022/02/18		B+	
ANGLE: NO DEC ± 1°		ENGR APPR: Gary Hsieh 2022/02/18		DWG NUMBER: BDX0035CMMMSXAU00	
.X ± 0.5°		MFG APPR:		REV 6	
.XX ± 0.25°		QA APPR:		SCALE: 4.5:1 SHEET 1 OF 4	
THIRD ANGLE					



Recommend PCB footprint

NOTES(UNLESS OTHERWISH SPECIFIED):

- 1.PADS TO BE ELECTROLESS NICKEL/IMMERSION GOLD (ENIG) PLATED
- 2.VIAS IN PAD AREAS MUST BE FILLED
- 3.INTERPOSER OUTLINE; NO COMPONENTS ALLOWED WITHIN THIS AREA
- 4.ALLOWED COMPONENT AREA; MAXIMUM COMPONENT HEIGHT 1.3 mm
- 5.IF SOLDERMASK IS APPLIED IN THE ARRAY AREA. IT SHALL NOT PROTRUDE ABOVE THE PLANE OF THE CONTACT PAD SURFACE

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Unimicron

DIMENSIONS ARE IN
MM

.X ± 0.15

.XX ± 0.10

.XXX ± 0.05

ANGLE: NO DEC ± 1°

.X ± 0.5°

.XX ± 0.25°

THIRD ANGLE

MATERIAL:

FINISH: --

DRAWN BY: Winni Cheng 2022/02/18

CHECKED BY: Jason Wu 2022/02/18

ENGR APPR: Gary Hsieh 2022/02/18

MFG APPR:

QA APPR:

TITLE:

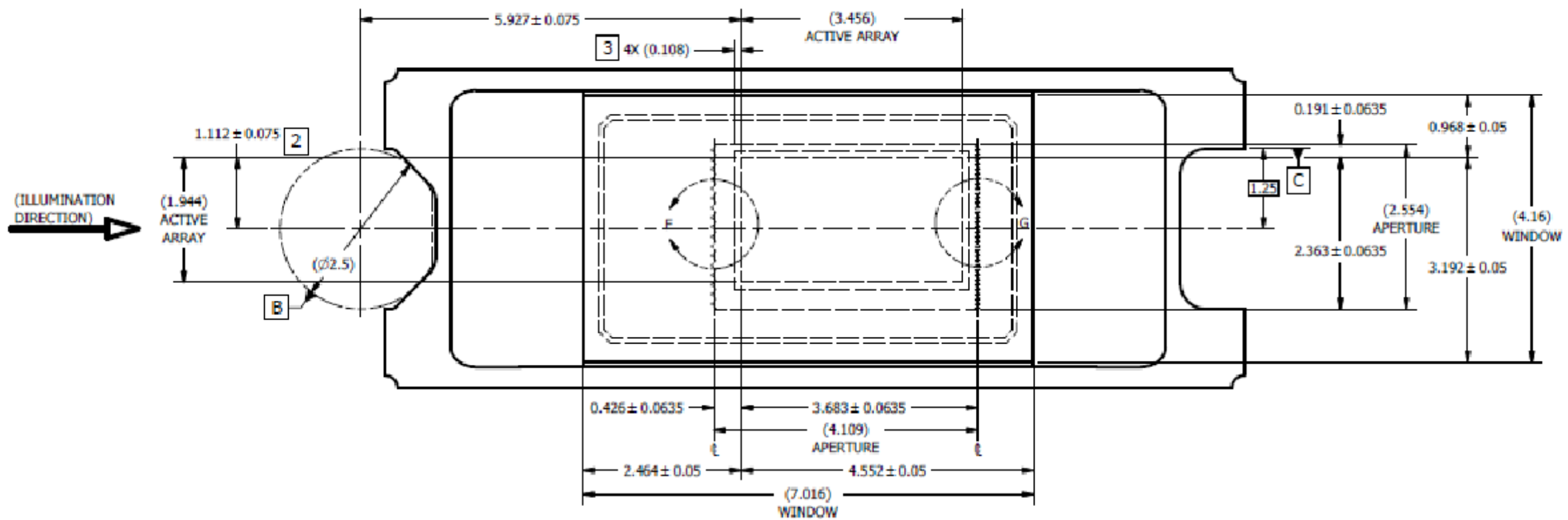
35 positions LGA-LGA PCBeam
interposer (0.7424 mm pitch)

DWG NUMBER: BDX0035CMMSXAU00

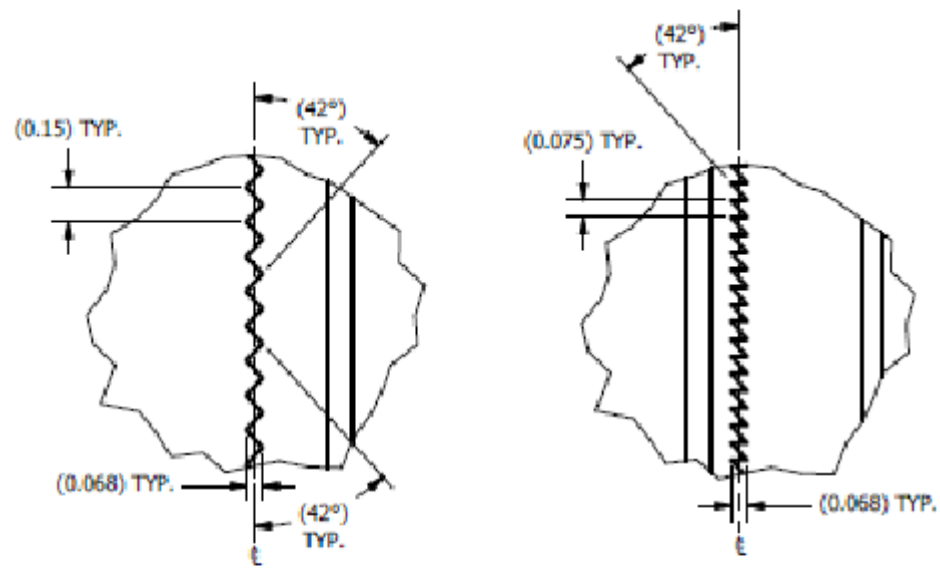
REV 6

SCALE: 12:1 SHEET 2 OF 4

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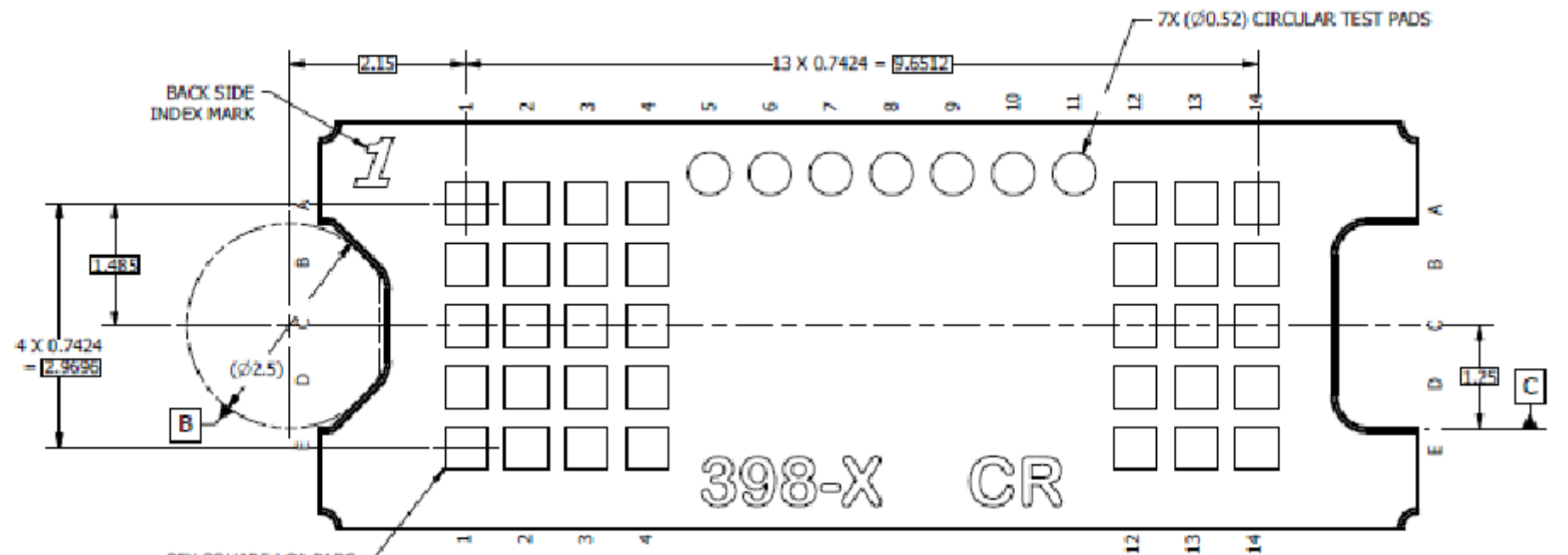


VIEW E
WINDOW AND ACTIVE ARRAY
(FROM SHEET 1)



DETAIL F
APERTURE LEFT EDGE
(WINDOW OMITTED FOR CLARITY)
SCALE 60 : 1

DETAIL G
APERTURE RIGHT EDGE
(WINDOW OMITTED FOR CLARITY)
SCALE 60 : 1



VIEW H-H
BACK SIDE METALLIZATION
(FROM SHEET 1)

DMD footprint

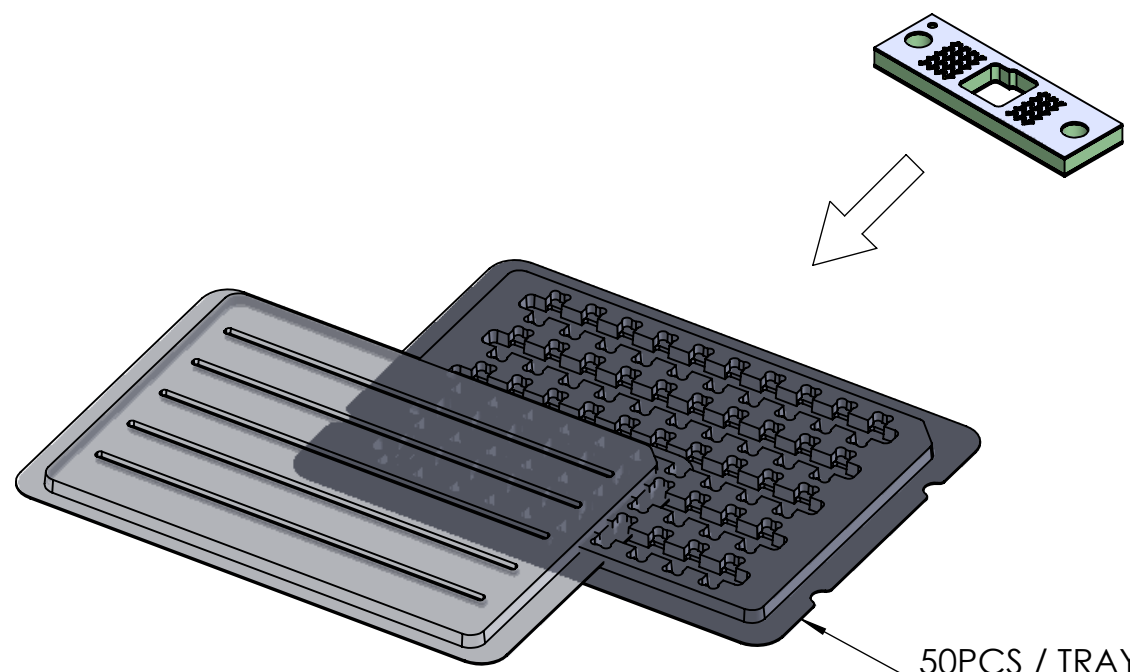
necconix
Unimicron

DIMENSIONS ARE IN
MM
.X ± 0.15
.XX ± 0.10
.XXX ± 0.05
ANGLE: NO DEC ± 1°
.X ± 0.5°
.XX ± 0.25°
THIRD ANGLE

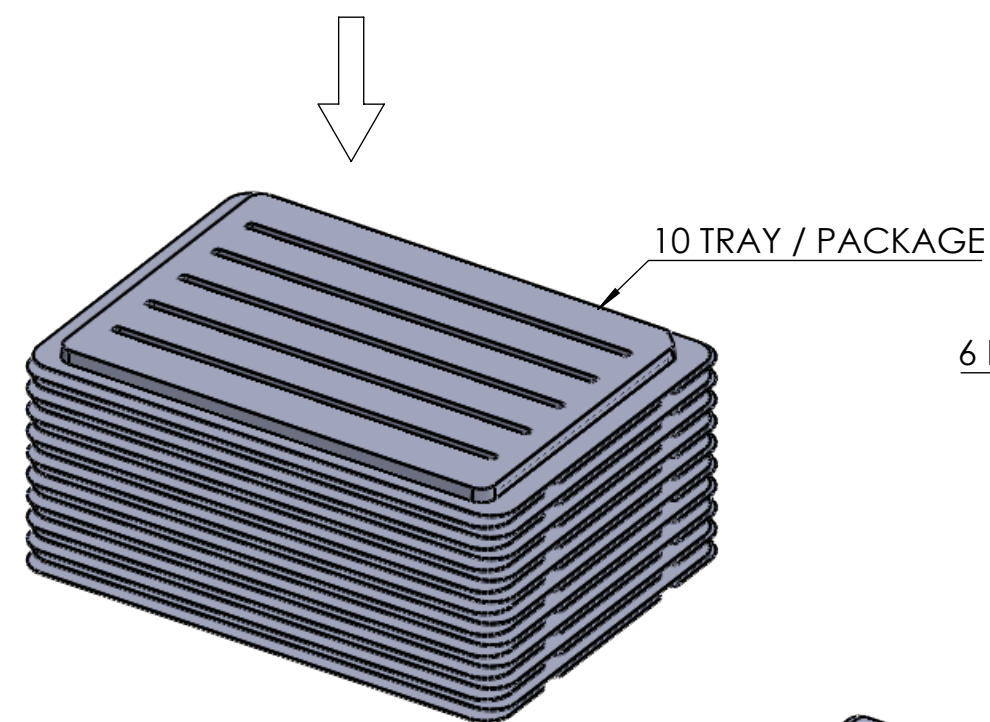
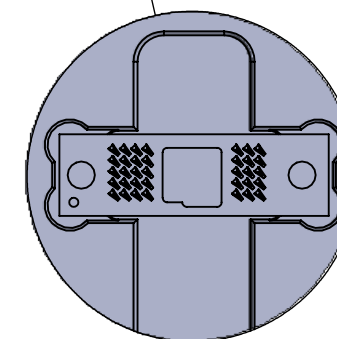
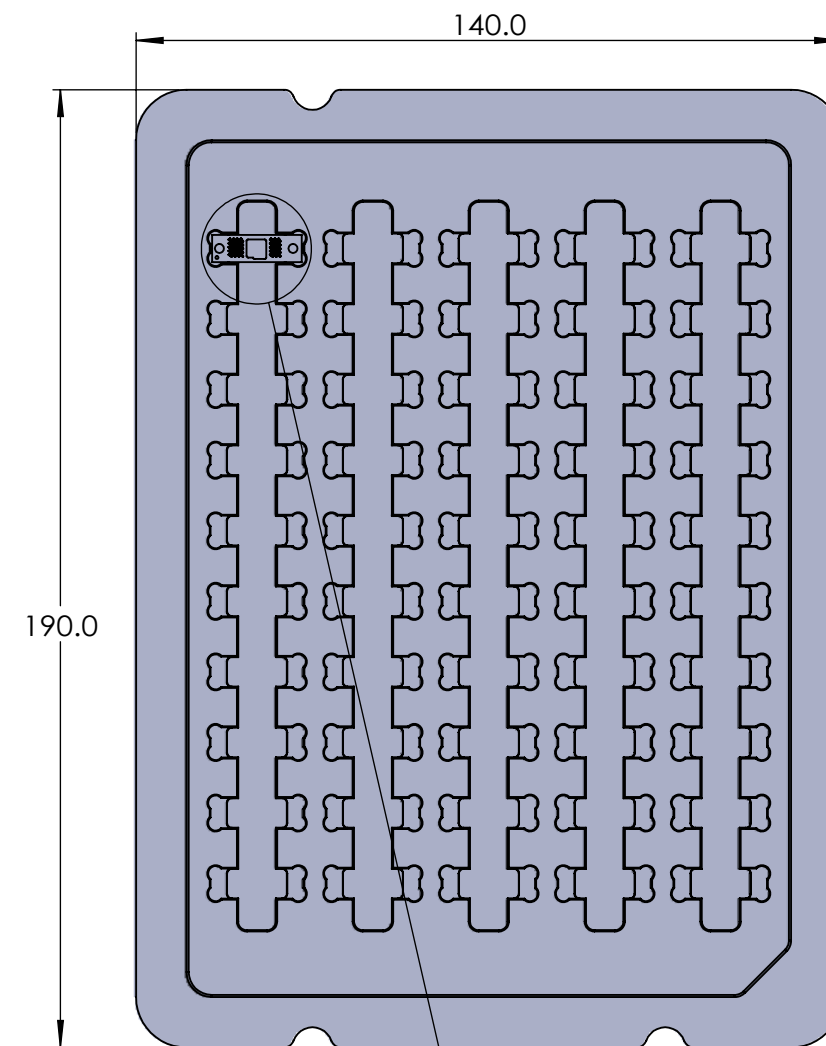
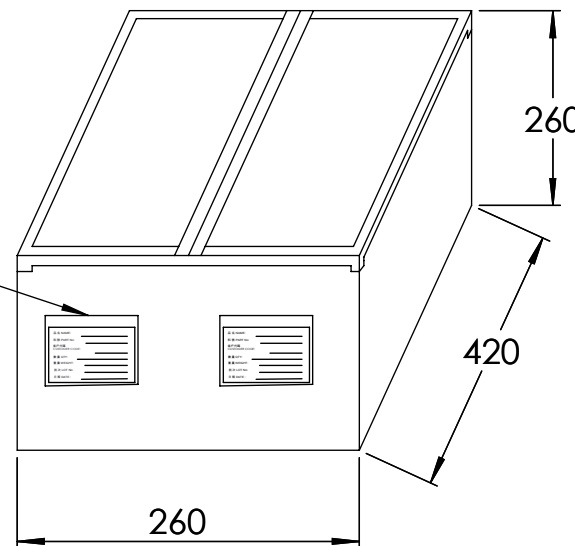
MATERIAL:
FINISH: --
DRAWN BY: Winni Cheng 2022/02/18
CHECKED BY: Jason Wu 2022/02/18
ENGR APPR: Gary Hsieh 2022/02/18
MFG APPR:
QA APPR:

TITLE:
35 positions LGA-LGA PCBeam
interposer (0.7424 mm pitch)
REV 6
DWG NUMBER: BDX0035CMMSXAU00
SCALE: 2.5:1 SHEET 3 OF 4

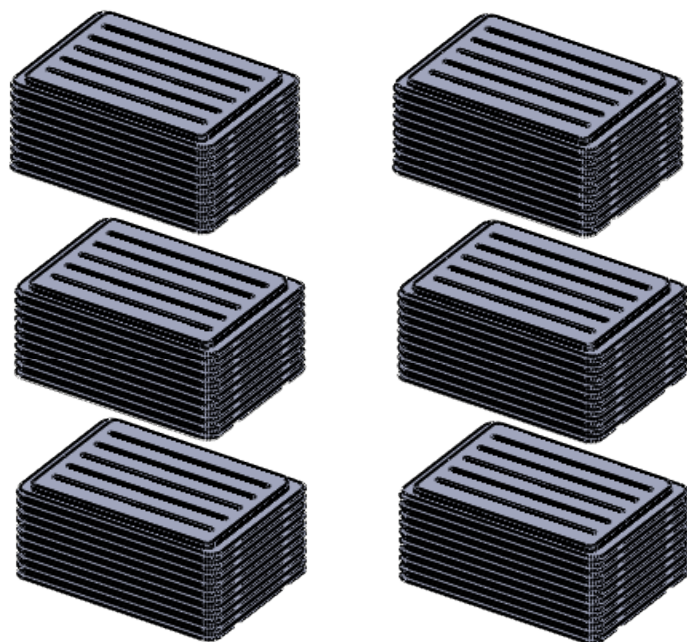
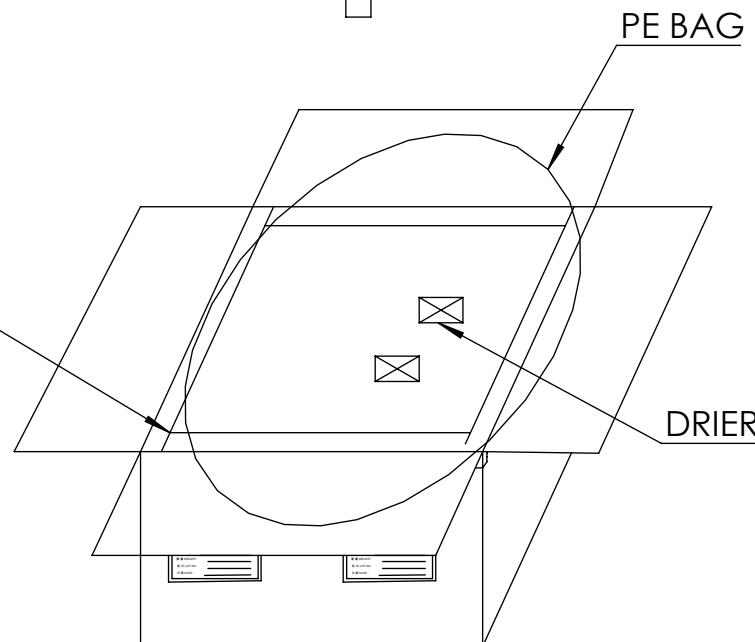
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CARTON LABELS



6 PACKAGE/CARTON



NOTE(UNLESS OTHERWISH SPECIFIED):
1.COMPONENT LOAD PER TRAY : 50PCS
10 TRAY/PACKAGE : 500PCS
6 PACKAGE/CARTON: 420mm X 260mm X 260mm.
TOTAL : 3000PCS/CARTON
2.MATERIAL : TRANSPARENT POLYSTYRENE(PS)

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DIMENSIONS ARE IN
MM [INCH]
.X ± 0.13 [.005]
.XX ± 0.08 [.003]
.XXX ± 0.04 [.001]
ANGLE: NO DEC ± 1°
.X ± 0.5°
.XX ± 0.25°
THIRD ANGLE

MATERIAL:	
FINISH: --	
DRAWN BY: Winni Cheng	2022/02/18
CHECKED BY: Jason Wu	2022/02/18
ENGR APPR: Gary Hsieh	2022/02/18
MFG APPR:	
QA APPR:	

TITLE:	
35 positions LGA-LGA PCBeam interposer (0.7424 mm pitch)	
SIZE: B+	DWG. NO.: BDX0035CMMSXAU00
REV: 6	SCALE: 2.5:1 SHEET 4 OF 4